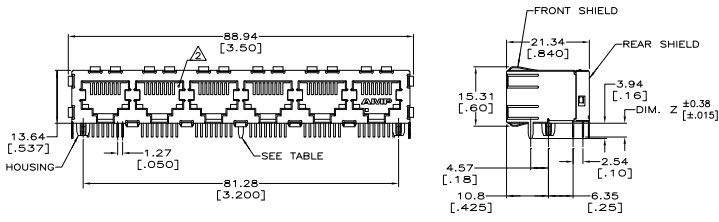
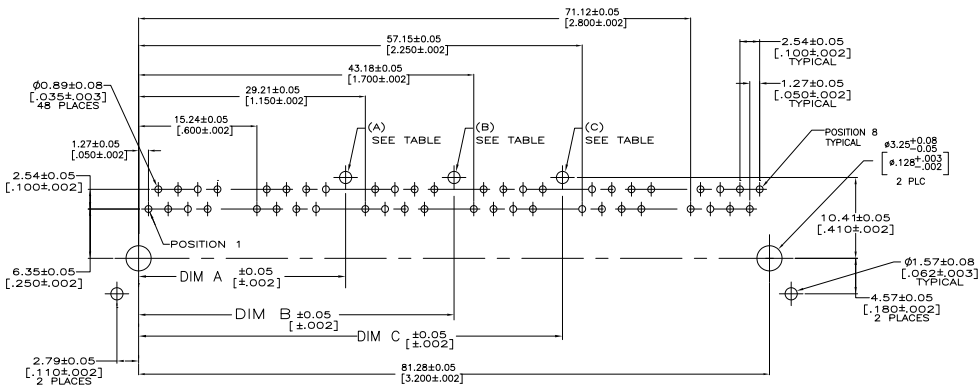


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REV	DATE	DESCRIPTION	BY	CHK
00				
D2		REVISED ECR-08-032447	DWAK2009	DZ SY
D3		REVISED PER ECO-10-000444	20JUN10	KK JHM



- △ MATERIAL: HOUSING - NYLON, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 μm[.000050] MINIMUM HARD GOLD IN LOCALIZED AREA AND 3.81 μm[.000150] MINIMUM MATTE TIN IN SOLDER AREA OVER 1.27 μm [0.000050] MINIMUM NICKEL UNDERPLATE. SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [0.000050] MINIMUM NICKEL AND 2.03 μm [0.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



RECOMMENDED PC BOARD LAYOUT
 COMPONENT SIDE (TOP)
 SCALE 4:1

OBsolete	Material	Dim Z	Dim A	Dim B	Dim C	Number or Rear PCB Shield Ground Tabs	Part No
△	3.56 (140)	26.67 (1.050)	40.64 (1.600)	54.61 (2.150)	3	5406206-3	
△	3.56 (140)	NA	40.64 (1.600)	NA	1	5406206-2	
△	3.56 (140)	NA	NA	NA	NONE	5406206-1	

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNED BY	REVIEWED BY	DATE
DR	DR	DATE
DATE	DATE	DATE
DATE	DATE	DATE
DATE	DATE	DATE
DATE	DATE	DATE

Customer Drawing: 100779, 5406206